

PCN# 20121102001
Qualification of Carsem Suzhou (CSZ) as Additional
Assembly and Test Site for TPD1E10B0XDPYR/T device
Change Notification / Sample Request

Date: 11/9/2012
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20121102001
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPD1E10B06DPYR	null
TPD1E10B09DPYR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20121102001	PCN Date:	11/09/2012
Title:	Qualification of Carsem Suzhou (CSZ) as Additional Assembly and Test Site for TPD1E10B0XDPYR/T device		

Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept:	Quality Services
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Proposed 1st Ship Date:	02/28/2013	Estimated Sample Availability:	Date Provided at Sample request
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Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

Qualification of Carsem Suzhou (CSZ) as Additional Assembly and Test Site for TPD1E10B0XDPYR/T device. Material differences are shown in the following table:

	JCET	CSZ
Mount compound	120402002600	438933
Mold Compound	120903003009	439086

The device in the product affected list is being qualified by similarity (see Qualification Data).
 Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.

Reason for Change:

Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site		
JCET China	Assembly Site Origin (22L)	ASO: JCE
Carsem Suzhou	Assembly Site Origin (22L)	ASO: CSZ

Sample product shipping label (not actual product label)



MADE IN: Malaysia
2DC: 20:

MSL '2 / 260C/1 YEAR	SEAL DT
MSL 1 / 235C/UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)T0:1750




(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) CSO: SHE (21L) CCO:USA
 (22L) ASO: MLA (23L) ACO: MYS

ASSEMBLY SITE CODES: JCET = F, [Carsem Suzhou](#) = F

Product Affected:			
TPD1E10B06DPYR	TPD1E10B06DPYT	TPD1E10B09DPYR	TPD1E10B09DPYT

Qualification Plan

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Schedule:	Start:	Nov 2012	End:	Feb 2013
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Qual Vehicle # 1: TPD1E10B09DPYR (MSL1-260C)

Package Construction Details

Assembly Site:	CARSEM SUZHOU	Mold Compound:	439086
# Pins-Designator, Family:	2-DPY, X2SON	Mount Compound:	438933
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.80 Mil Dia., Au

Qualification: **Plan** **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
**High Temp. Storage Bake	170C (420hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Solderability	Steam age, 8 hours, Pb-Free solder	22/0	22/0	22/0
Physical Dimensions	(per mechanical drawing)	5/0	5/0	5/0
Bond Pull	76 Wire, 3 units min	76/0	76/0	76/0
X-ray	(top side only)	5/0	5/0	5/0
Manufacturability	(per mfg. Site specification)	1/0	1/0	1/0
Moisture Sensitivity	(level 1 @ 260C peak +5/-0C)	12/0	12/0	12/0

Notes ** - Preconditioning sequence: Level 1-260C.

Reference Qualification Data:

Qualification Data: Approved 08/03/2012

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle : TPD1E6B06DPLR (MSL1-260C)

Package Construction Details

Assembly Site:	CARSEM SUZHOU	Mold Compound:	439086
# Pins-Designator, Family:	2-DPL, X2SON	Mount Compound:	438933
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.80 Mil Dia., Au

Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
**High Temp. Storage Bake	170C (420hrs)	77/0	77/0	77/0
Life Test	150C (300 Hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
**Thermal Shock	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Salt Atmosphere	24 hr	22/0	22/0	22/0
Solderability	Steam age, 8 hours, Pb-Free solder	22/0	22/0	22/0
Physical Dimensions	(per mechanical drawing)	5/0	5/0	5/0
Bond Strength	76 Wire, 3 units min	76/0	76/0	76/0
X-ray	(top side only)	5/0	5/0	5/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 1 @ 260C peak +5/-0C)	12/0	12/0	12/0
Notes ** - Preconditioning sequence: Level 1-260C.				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com